

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	
<b>Filing Date:</b>	
<b>Title of Invention:</b>	EPOXY RESIN MOLDING MATERIAL FOR SEALING AND ELECTRONIC COMPONENT
<b>First Named Inventor:</b>	Kazuyoshi Tendou
<b>Filer:</b>	Joerg-Uwe V. Szpil/Bridget Burke
<b>Attorney Docket Number:</b>	MIYOSH0006

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				900